



Attorney Docket: 2022/48819  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bulent M. Basol et al.

Serial No.: 09/671,800

Group Art Unit: 1741

Filed: September 28, 2000

Examiner: W. Leader

Title: PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL  
COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE AND  
LAYER STRUCTURE MADE THEREBY

ADDITIONAL CLAIMS FEE CHART

Commissioner for Patents  
Washington, D.C. 20231

Transmitted herewith is a Supplemental Reply for filing and  
the filing fee is calculated below:

For	No. After Amendment	Highest No. Prev. Filed	No. Extra	Rate Fee
Total Claims	91	88	3	\$ 9/\$18 = \$54
Indep. Claims	14	14	0	\$40/\$80 = \$ 0
Multiple Dependent Claim Presented				\$135/\$270=\$ 0
TOTAL:				\$54

XX A check in the amount of \$54.00 is enclosed.

XX The Commissioner is hereby authorized to charge any additional  
fees which may be required, or credit any overpayment, to Account  
No. 05-1323 (Docket #2022/48819). A duplicate copy of this sheet  
is attached.

Respectfully submitted,

November 13, 2002

Richard R. Diefendorf  
Registration No. 32,390

CROWELL & MORING LLP  
P.O. Box 14300  
Washington, D.C. 20044-4300  
Telephone No.: (202) 624-2500  
Facsimile No.: (202) 628-8844  
RRD:msy

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TC 1700 MAIL ROOM



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MATERIAL COATING OVER THE TOP SURFACE OF A  
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THEREBY

SUPPLEMENTAL REPLY

Commissioner for Patents  
Washington, D.C. 20231

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Supplemental to the Reply filed November 12, 2002, electing the invention defined by claims 17-22, 58-60, 66, and 73-76 (invention II) for examination, kindly amend the claims of this application as follows.

Please cancel claims 20 and 60.

Please amend claims 17-19, 21, 58 and 59 as follows. A marked-up version of the amended claims is included at the end of this document.

11/14/2002 SSESHE1 00000015 09671800

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54.00 OP

17. (Amended) A layer structure usable in manufacturing an integrated circuit made by a process comprising:

providing a patterned substrate,

supplying an electrolyte solution out of which a conductive material can be plated, under an applied potential, over a surface of said patterned substrate,